



# **VRoHS**

# **FEATURES**

- Inches H<sub>2</sub>O Pressure Ranges
- PCB Mountable
- Digital Output
- Barbed Pressure Ports

#### **APPLICATIONS**

- Blocked Filter Detection
- Altitude and Airspeed Measurements
- Medical Instruments
- Fire Suppression System
- Panel Meter
- Air Movement/Environmental Controls
- Pneumatic Controls

# **MS4515DO**

#### **SPECIFICATIONS**

- PCB Mounted Digital Output Transducer
- Combination Temperature and Pressure
- Pressure Ranges from 2 to 30 inches H<sub>2</sub>O
- I<sup>2</sup>C or SPI Protocol
- Differential & Gage
- Temperature Compensated
- 3.3 or 5.0 V<sub>DC</sub> Supply Voltage
- Low Power Option Available (standby < 1μA)</li>

The MS4515DO is a small, ceramic based, PCB mounted pressure transducer from TE Connectivity. The transducer is built using the latest CMOS sensor conditioning circuitry to create a low cost, high performance digital output pressure (14bit) and temperature (11bit) transducer designed to meet the strictest requirements from OEM customers.

The MS4515DO is fully calibrated and temperature compensated with a total error band (TEB) of less than 1.0% over the compensated range. The sensor operates from single supply of either 3.3 or  $5.0V_{DC}$  and requires a single external component for proper operation.

The rugged ceramic transducer is available in side port, top port, and manifold mount and can measure gage or differential pressure from 2 to 30 inches  $H_2O$ . The 1/8" barbed pressure ports mate securely with 3/32" ID tubing.

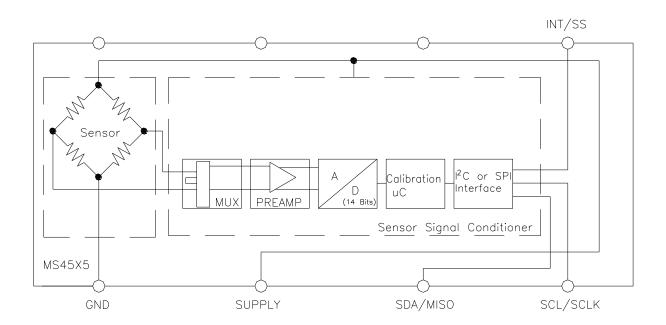


# STANDARD RANGES (INCHES H<sub>2</sub>O)

| Range | Gage           | Differential   | Option Availability |
|-------|----------------|----------------|---------------------|
| 2     |                | DS, SS, TP, MM | -L                  |
| 4     | DS, SS, TP, MM | DS, SS, TP, MM | -L                  |
| 5     | DS, SS, TP, MM | DS, SS, TP, MM | -L                  |
| 10    | DS, SS, TP, MM | DS, SS, TP, MM | -F, -L, -M          |
| 20    | DS, SS, TP, MM | DS, SS, TP, MM | -F, -L, -M          |
| 30    | DS, SS, TP, MM | DS, SS, TP, MM | -F, -L, -M          |

See Package Configurations: DS= Dual Side Port, SS= Single Side Port, TP= Top Port, MM= Manifold Mount Only I<sup>2</sup>C Protocol is Available on "L" type Pin Styles; Reference Ordering Information for Details Pin Style "L" is only available SS and MM port types. Pin Style "C" is only available SS, TP and MM port types.

#### **BLOCK DIAGRAM**





# **ABSOLUTE MAXIMUM RATINGS**

| Parameter           | Conditions                           | Min    | Max        | Unit | Notes          |
|---------------------|--------------------------------------|--------|------------|------|----------------|
| Supply Voltage      | T <sub>A</sub> = 25 °C               | 2.7    | 5.5        | V    |                |
| Output Current      | $T_A = 25^{\circ}C$                  |        | 3          | mA   |                |
| Storage Temperature |                                      | -40    | +125       | °C   |                |
| Humidity            | $T_A = 25^{\circ}C$                  |        | 95         | %RH  | Non Condensing |
| Overpressure        | $T_A = 25  ^{\circ}C$ , both Ports   | Not to | Exceed 300 | psi  |                |
| Burst Pressure      | $T_A = 25 ^{\circ}\text{C}$ , Port 1 |        |            | psi  | See Table 1    |
| ESD                 | HBM                                  | -4     | +4         | kV   | EN 61000-4-2   |
|                     |                                      |        |            |      |                |

Solder Temperature 250°C, 5 sec max.

### TABLE 1: BURST PRESSURE BY RANGE AND PACKAGE STYLE

| Style | Port   | 002 | 004 | 005 | 010 | 020 | 030 | Unit |
|-------|--------|-----|-----|-----|-----|-----|-----|------|
| DS,MM | Port 1 | 10  | 10  | 10  | 10  | 10  | 20  | PSI  |
|       | Port 2 | 10  | 10  | 10  | 10  | 10  | 20  | PSI  |
| SS,TP | Port 1 |     | 10  | 10  | 10  | 10  | 20  | PSI  |

# **ENVIRONMENTAL SPECIFICATIONS**

| Parameter            | Conditions  |
|----------------------|---|
| Mechanical Shock     | Mil Spec 202F, Method 213B, Condition C, 3 Drops              |
| Mechanical Vibration | Mil Spec 202F, Method 214A, Condition 1E, 1Hr Each Axis       |
| Thermal Shock        | 100 Cycles over Storage Temperature, 30 minute dwell          |
| Life                 | 1 Million FS Cycles   |
| MTTF                 | >10Yrs, 70 °C, 1.188 Million Pressure Cycles, 120%FS Pressure |



#### PERFORMANCE SPECIFICATIONS

Supply Voltage<sup>1</sup>: 5.0V or 3.3 V<sub>DC</sub>

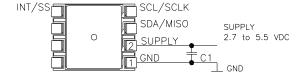
Reference Temperature: 25°C (unless otherwise specified)

| PARAMETERS                          | MIN  | TYP          | MAX          | UNITS     | NOTES |  |
|-------------------------------------|--|--------------|--------------|-----------|-------|--|
| Output                              | 51E<br>1EB   |              | 3AE0<br>3EB  | Count Hex | 1,2,3 |  |
| Span                                | 31EA<br>3852   | 3333<br>3998 | 347A<br>3AE0 | %Span     | 1,2,3 |  |
| Pressure Accuracy                   | -0.25  |              | 0.25         | %Span     | 2     |  |
| Total Error Band (TEB)              | -1.0   |              | 1.0          | %Span     | 3,7   |  |
| TEB (4inH20 and Below)              | -2.0   |              | 2.0          | %Span     | 3,7   |  |
| Temperature Accuracy                |  | 1.5          |              | ōC        | 4     |  |
| Supply Current                      |  | 3            |              | mA        | 7     |  |
| Load Resistance (R <sub>L</sub> )   | 10   |              |              | kΩ        |       |  |
| Long Term stability (Offset & Span) |  | ±0.5         |              | %Span     |       |  |
| Compensated Temperature             | 0  |              | +60          | ōC        | 5     |  |
| Operating Temperature               | -10  |              | +85          | ∘C        |       |  |
| Output Pressure Resolution          |  |              | 14           | bits      |       |  |
| Output Temperature Resolution       | 8  |              | 11           | bits      |       |  |
| Update Time                         |  | 0.5          |              | ms        | 6     |  |
| Start Time to Data Ready            |  |              | 8.4          | ms        | 6     |  |
| Weight                              |  |              | 3            | grams     |       |  |
| Media                               | Non-Corrosive Dry Gases Compatible with Ceramic, Silicon, Borosilicate Glass, Media RTV, Gold, Aluminum and Epoxy. See "Wetted Material by Port Designation" chabelow. |              |              |           |       |  |

#### Notes

- 1. Proper operation requires an external capacitor placed as shown in Connection Diagram. Output is not ratiometric to supply voltage.
- 2. The maximum deviation from a best fit straight line (BFSL) fitted to the output measured over the pressure range at 25C. Includes all errors due to pressure non linearity, hysteresis, and non-repeatability.
- 3. Total pressure error band includes all accuracy errors, thermal errors over the compensated temperature range and span and offset calibration tolerances. For ideal sensor output with respect to input pressure and temperature, reference Transfer Function charts below. TEB values are valid only at the calibrated supply voltage.
- 4. The deviation from a best fit straight line (BFSL) fitted to the output measured over the compensated temperature range.
- 5. For errors beyond the compensated temperature range, see Extended Temperature Multiplier chart below.
- 6. Start time to data ready is the time to get valid data after POR (power on reset). The time to get subsequent valid data is then specified by the update time specification.
- 7. This product can be configured for custom OEM requirements, contact factory for lower power consumption or higher accuracy.

#### **CONNECTION DIAGRAM**



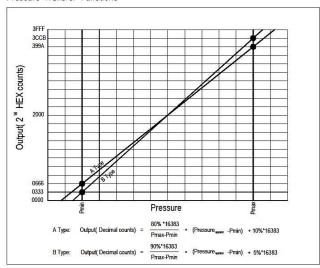
#### **Notes**

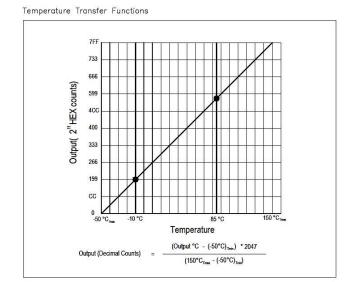
1. Place 100nF capacitor between Supply and GND to within 2 cm of sensor.



### PRESSURE AND TEMPERATURE TRANSFER FUNCTION

Pressure Transfer Functions





Sensor Output at Significant Percentages

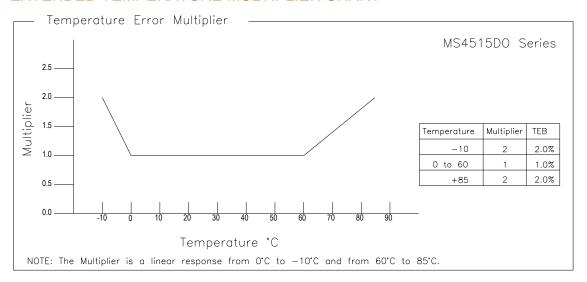
| % of Count | Output Type A (inH20)   | Output Type B (inH20)  | Digital Counts (decimal) | Digital Counts (hex) |
|------------|---|--|--------------------------|----------------------|
| 0          | P <sub>MIN</sub> -(P <sub>MAX</sub> -P <sub>MIN</sub> )*10/80 | P <sub>MIN</sub> -(P <sub>MAX</sub> -P <sub>MIN</sub> )*5/90 | 0                        | 0X0000               |
| 5          |   | P <sub>MIN</sub>   | 819                      | 0X0333               |
| 10         | P <sub>MIN</sub>  |  | 1638                     | 0X0666               |
| 50         |   |  | 8192                     | 0X2000               |
| 90         | P <sub>MAX</sub>  |  | 14746                    | 0X399A               |
| 95         |   | P <sub>MAX</sub>   | 15563                    | 0X3CCB               |
| 100        | P <sub>MAX</sub> +(P <sub>MAX</sub> -P <sub>MIN</sub> )*10/80 | $P_{MAX} + (P_{MAX} - P_{MIN}) * 5/90$                       | 16383                    | 0X3FFF               |

**Temperature Output vs Counts** 

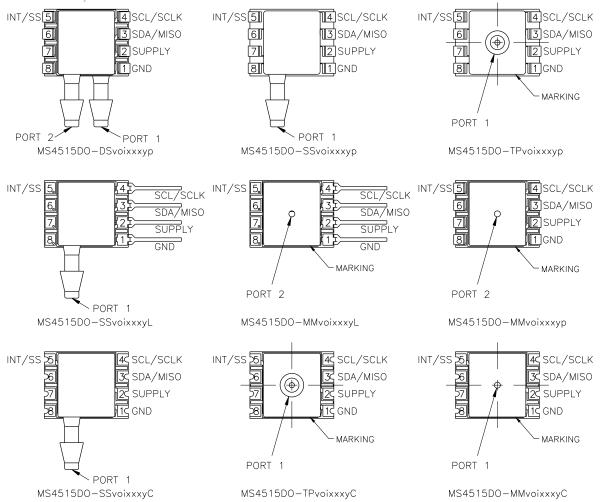
| OUTPUT (°C) | Digital Count (decimal) | Digital Counts (hex) |
|-------------|-------------------------|----------------------|
| -50         | 0                       | 0X0000               |
| 0           | 511                     | 0X01FF               |
| 10          | 614                     | 0X0266               |
| 25          | 767                     | 0X02FF               |
| 50          | 1023                    | 0X03FF               |
| 85          | 1381                    | 0X0565               |
| 150         | 2047                    | 0X07FF               |



#### EXTENDED TEMPERATURE MULTIPLIER CHART



### PACKAGE, PINOUT & PRESSURE TYPE CONFIGURATION





| Pin | Name   | Pin | Function                                   |
|-----|--------|-----|--|
| G   | iND    | 1   | Ground                                     |
| SUI | SUPPLY |     | Positive Supply Voltage                    |
| SDA | MISO   | 3   | I <sup>2</sup> C Data SPI Data             |
| SCL | SCLK   | 4   | I <sup>2</sup> C Clock SPI Clock           |
| INT | SS     | 5   | I <sup>2</sup> C Interrupt SPI Chip Select |
|     |        | 6-8 | No Connection                              |

INT is not available for Pin Style "L" models

| Pressure Type                  | $P_{min}$           | $P_{max}$           | Description  |
|--------------------------------|---------------------|---------------------|--|
| Differential/<br>Bidirectional | -P <sub>range</sub> | +P <sub>range</sub> | Output is proportional to the difference between Port 1 and Port 2. Output swings positive when Port 1> Port 2. Output is 50% of total counts when Port 1=Port 2 |
| Gauge                          | 0psiG               | +P <sub>range</sub> | Output is proportional to the difference between 0psiG (Pmin) and Port 1. Output swings positive when Port 1> Port 2.  |

Prange is equal to the maximum full scale pressure specified in the ordering information.

Standard Range (inH<sub>2</sub>O) by port style

# WETTED MATERIAL BY PORT DESIGNATION

|            | Material |         |         |                    |     |      |          |       |
|------------|----------|---------|---------|--------------------|-----|------|----------|-------|
| Style      | Port     | Ceramic | Silicon | Borosilicate Glass | RTV | Gold | Aluminum | Ероху |
| DS. MM     | Port 1   | X       | Χ       | X                  | Χ   |      |          | Χ     |
| D3, IVIIVI | Port 2   | X       | Χ       | X                  | Χ   | X    | X        | Χ     |
| SS, TP, SM | Port 1   | X       | Χ       | Χ                  | Χ   | Χ    | X        | Χ     |

<sup>&</sup>quot;X" Indicates Wetted Material



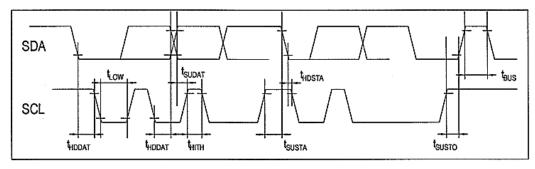
# I<sup>2</sup>C INTERFACE

#### I<sup>2</sup>C Interface Parameters

| Parameters                                      | Symbol             | Min | Тур | Max | Units |
|---|--------------------|-----|-----|-----|-------|
| SCLK Clock Frequency                            | FSCL               | 100 |     | 400 | kHz   |
| Start Condition hold time relative to SCL edge  | t <sub>HDSTA</sub> | 0.1 |     |     | μs    |
| Minimum SCL clock low width <sup>1</sup>        | $t_{LOW}$          | 0.6 |     |     | μs    |
| Minimum SCL clock high width <sup>1</sup>       | t <sub>HIGH</sub>  | 0.6 |     |     | μs    |
| Start Condition Setup time relative to SCL edge | t <sub>SUSTA</sub> | 0.1 |     |     | μs    |
| Data hold time on SDA relative to SCL edge      | t <sub>HDDAT</sub> | 0   |     |     | μs    |
| Data setup time on SDA relative to SCL edge     | t <sub>SUDAT</sub> | 0.1 |     |     | μs    |
| Stop condition setup time on SCL                | t <sub>SUSTO</sub> | 0.1 |     |     | μs    |
| Bus free time between stop and start condition  | $t_{BUS}$          | 2   |     |     | μs    |

<sup>&</sup>lt;sup>1</sup> combined low and high widths must equal or exceed minimum SCL period

#### 12C INTERFACE TIMING DIAGRAM





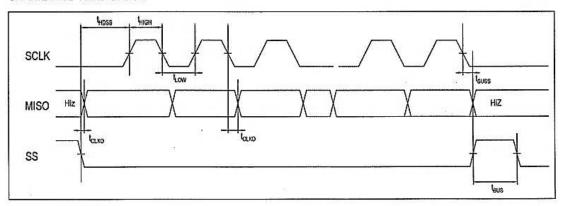
# SPI INTERFACE

#### **SPI Interface Parameters**

| Parameters                             | Symbol            | Min | Тур | Max | Units |
|--|-------------------|-----|-----|-----|-------|
| SCLK Clock Frequency                   | FSCL              | 50  |     | 800 | kHz   |
| SS Drop to First clock edge            | t <sub>HDSS</sub> | 2.5 |     |     | μs    |
| Minimum SCL clock low width @1         | t <sub>LOW</sub>  | 0.6 |     |     | μs    |
| Minimum SCL clock high width @1        | t <sub>HIGH</sub> | 0.6 |     |     | μs    |
| Clock Edge to data transition          | t <sub>CLKD</sub> | 0   |     | 0.1 | μs    |
| Rise of SS relative to last clock edge | t <sub>suss</sub> | 0.1 |     |     | μs    |
| Bus free time rise and fall of SS      | t <sub>BUS</sub>  | 2   |     |     | μs    |

<sup>@1</sup> combined low and high widths must equal or exceed minimum SCLK period

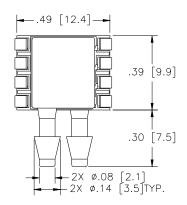
#### SPI INTERFACE TIMING DIAGRAM

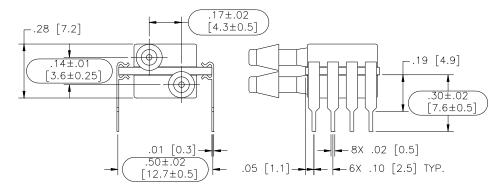




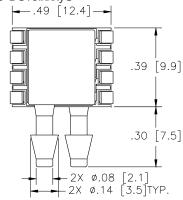
#### **DIMENSIONS**

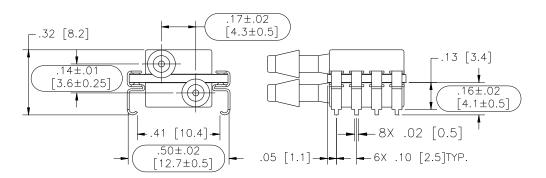
Dimensions are in INCHES [mm] Model: MS4515DO-DSvoixxxyP





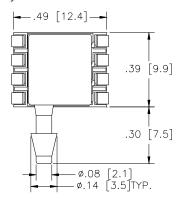
#### Model: MS4515DO-DSvoixxxyS

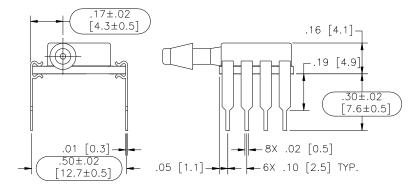




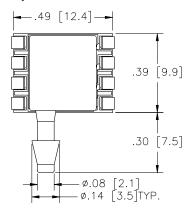


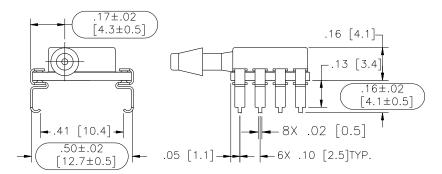
#### Model: MS4515DO-SSvoixxxyP





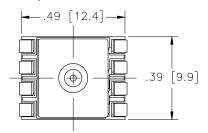
#### Model: MS4515DO-SSvoixxxyS

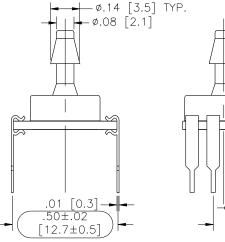


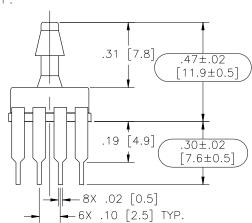




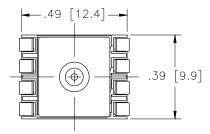
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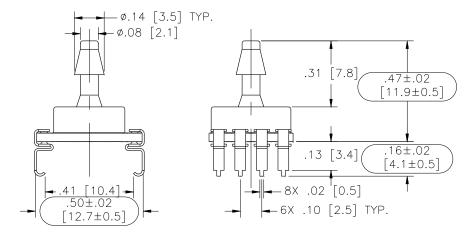






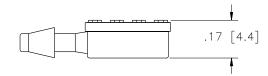
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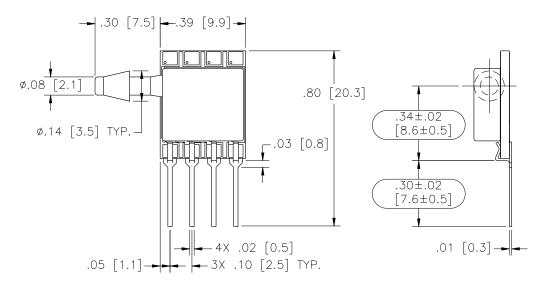




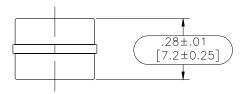


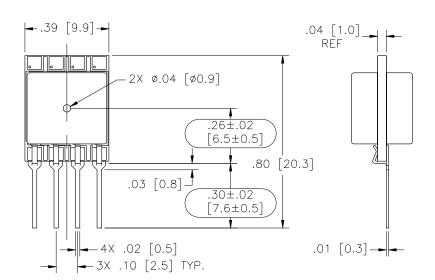
Model: MS4515DO-SSvoixxxyL





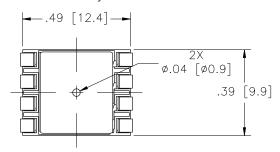
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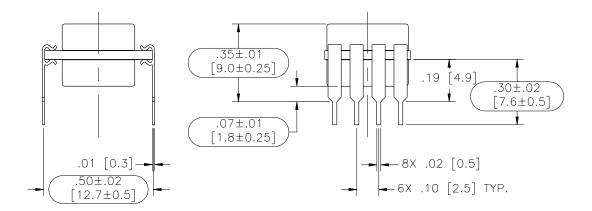




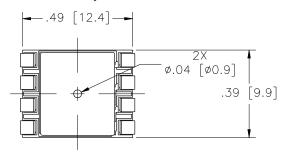


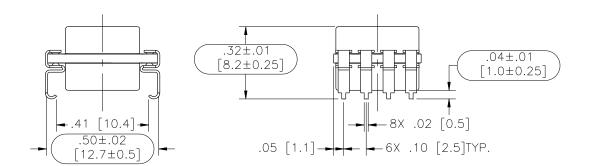
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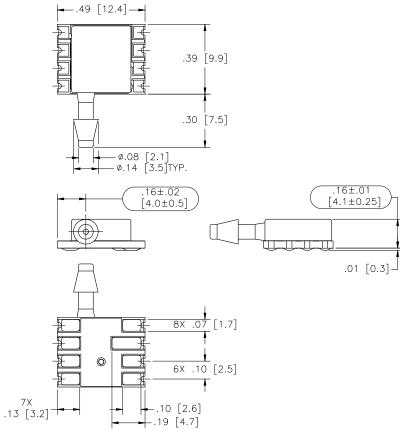
#### Model: MS4515DO-MMvoixxxyS



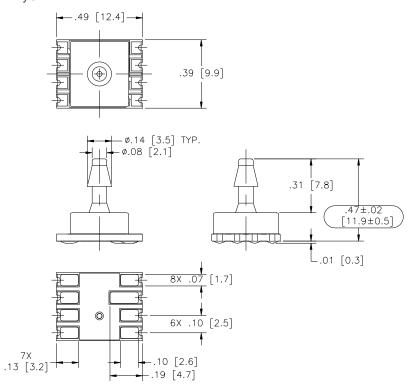




Model: MS4515DO-SSvoixxxyC

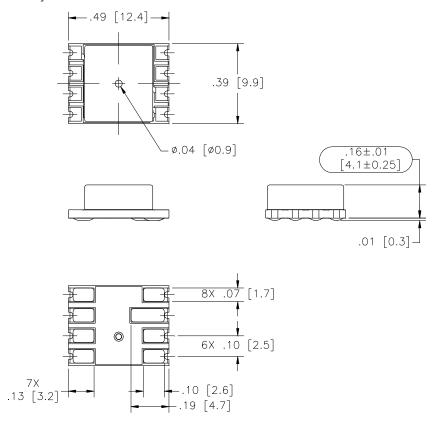


Model: MS4515DO-TPvoixxxyC





Model: MS4515DO-MMvoixxxyC





#### **APPLICATION NOTES**

Measurement Specialties offers a comprehensive selection of product support documentation.

#### MS45xx Series Application Note

- Bypass Capacitor Selection
- Pressure Hose Recommendations
- PCB Layout Recommendations

#### Interfacing to MEAS Digital Pressure Modules

- I<sup>2</sup>C or SPI Protocol Description
- Data Fetch, Measurement Request Commands
- Timing Diagrams

#### Configuration, POR and Power Consumption

- Standard and Low Power Configuration
- Power On Reset (POR)
- Current Consumption by Sampling Frequency

#### **AVAILABLE OPTIONS**

### Gel Coat (-F Option)

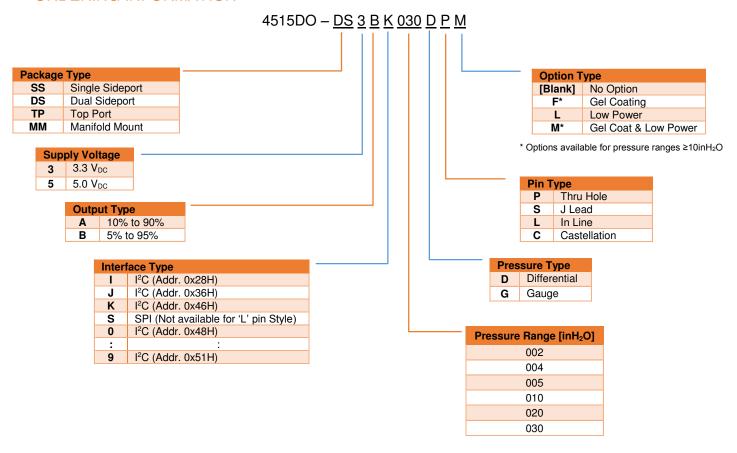
The MS4515DO is designed for non-ionic and clean dry air applications. Select this option for added protection in high humidity or slightly corrosive environments with the application of a silicone gel elastomer to sensor and ASIC. For questions concerning media compatibility, contact the factory.

#### Low Power (-L Option)

Select this option for battery powered or handheld device applications. In this configuration, the sensor and calibration microcontroller are powered down, drawing a current of  $\sim 0.6 uA$  (Vs=5.0 V<sub>DC</sub>). When the master sends a **Read MR** (measurement request) command (I<sup>2</sup>C or SPI); the sensor is "awaken" and begins the measurement cycle; data is then placed onto the output registers. The sensor and calibration microcontroller are powered down again, awaiting the **Read DF** (data fetch) command from the master.



#### **ORDERING INFORMATION**







- ■カタログに掲載してある製品の色は印刷インキの関係上、実際とは異なる場合があります。
- ■製品のデザイン、仕様等などは、予告なく変更する場合があります。

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